

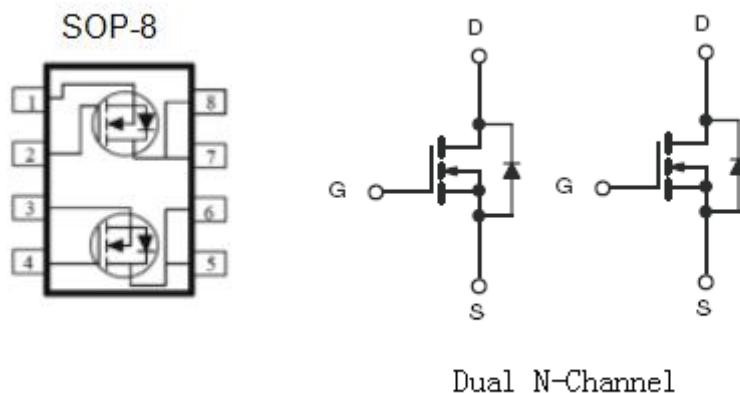
1. Features

- $R_{DS(on)}=14.5\text{m}\Omega(\text{typ})$ @ $V_{GS}=10\text{ V}$
- Super low gate charge
- Green device available
- Excellent Cdv/dt effect decline
- Advanced high cell density trench technology

2. Description

The KNE4603A2 is the high cell density trenched Dual N-channel MOSFET, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The KNE4603A2 meet the RoHs and Green Product requirement.

3. Symbol



Dual N-Channel

4. Absolute maximum ratings

($T_A=25^\circ\text{C}$,unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-source voltage	V_{DSS}	30	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current $V_{GS}@10\text{V}^1$	I_D	7.0	A
$T_A=70^\circ\text{C}$		5.6	
Pulsed drain current ²	I_{DM}	35	A
Single pulse avalanche energy ³	E_{AS}	20	mJ
Avalanche current	I_{AS}	20	A
Total power dissipation ⁴	P_D	1.5	W
Junction and storage temperature range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$
Thermal resistance-junction to ambient ¹	$R_{\theta JA}$	85	$^\circ\text{C/W}$
Thermal resistance-junction to case ¹	$R_{\theta JC}$	25	$^\circ\text{C/W}$

5.Electrical characteristics

($T_J=25^\circ\text{C}$,unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-Source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	30	-	-	V
BV_{DSS} Temperature coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	-	0.034	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V},$ $T_J=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V},$ $T_J=55^\circ\text{C}$	-	-	5	
Gate-source leakage current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.5	2.5	V
$V_{\text{GS}(\text{th})}$ Temperature coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	3.84	-	$\text{mV}/^\circ\text{C}$
Static drain-source on- resistance ²	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=7\text{A}$	-	14.5	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$	-	20	28	
Forward transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=7\text{A}$	-	6.2	-	S
Diode forward voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A},$ $T_J=25^\circ\text{C}$	-	-	1.2	V
Gate resistance	R_g	$V_{\text{DS}}=0\text{V},$ $V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	1.04	2.1	Ω
Total gate charge(4.5V)	Q_g	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=4.5\text{V}$ $I_{\text{D}}=7\text{A}$	-	6		nC
Gate-source charge	Q_{gs}		-	2.2		
Gate-drain charge	Q_{gd}		-	2		
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V},$ $R_g=3.3\Omega, V_{\text{GS}}=10\text{V}$ $I_{\text{D}}=7\text{A}$	-	1.2		ns
Rise time	t_r		-	40		
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	18		
Fall time	t_f		-	7.2		
Input capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=15\text{V}$ $F=1.0\text{MHz}$	-	583		pF
Output capacitance	C_{oss}		-	77		
Reverse transfer capacitance	C_{rss}		-	59		
Diode characteristics						
Continuous source current ^{1.5}	I_s	$V_G=V_D=0\text{V}, \text{Force current}$	-	-	7	A
Pulsed source current ^{2.5}	I_{SM}		-	-	35	A
Reverse recovery time	t_{rr}	$I_F=7\text{A}, dI/dt=100\text{A/us},$ $T_J=25^\circ\text{C}$	-	7.2	-	nS
Reverse recovery charge	Q_{rr}		-	2.9	-	nC

Note:1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed, pulse width $\leq 300\text{us}$,duty cycle $\leq 2\%$.
3. The EAS data shows Max.rating. The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$. $I_{\text{AS}}=20\text{A}$.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_{D} and I_{DM} , in real applications, should be limited by total power dissipation.

6. Test circuits and waveforms

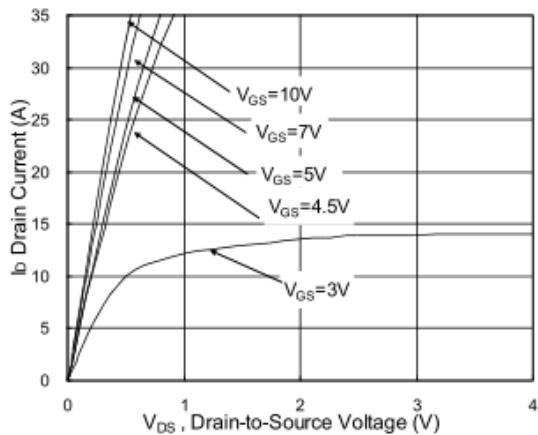


Fig.1 Typical Output Characteristics

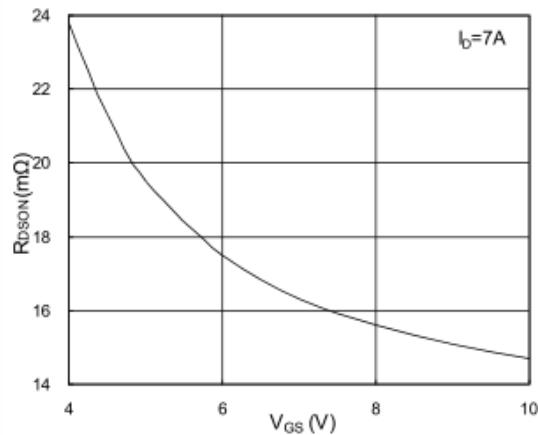


Fig.2 On-Resistance vs. Gate-Source

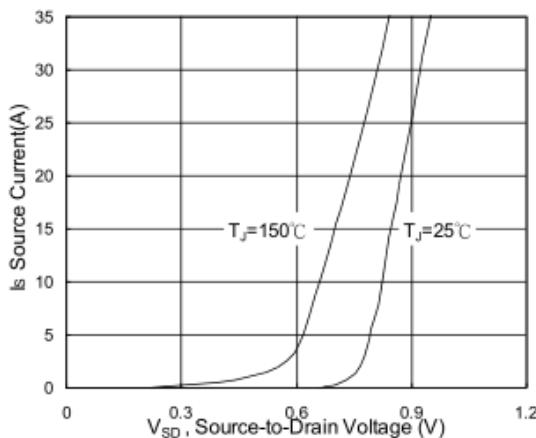


Fig.3 Forward Characteristics Of Reverse

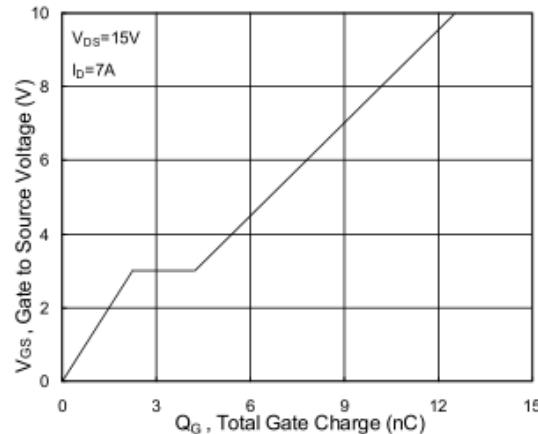


Fig.4 Gate-Charge Characteristics

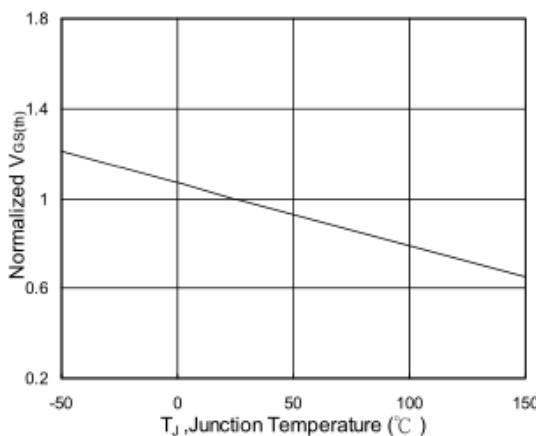


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

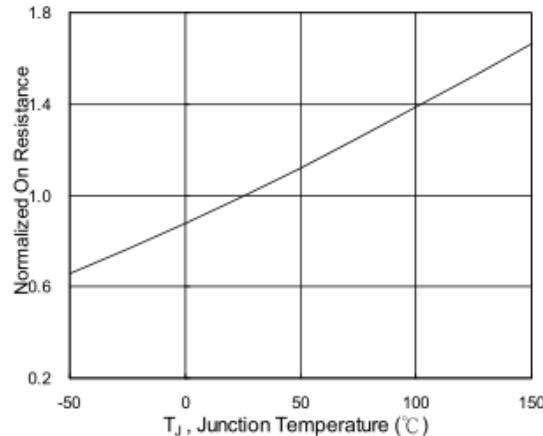


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

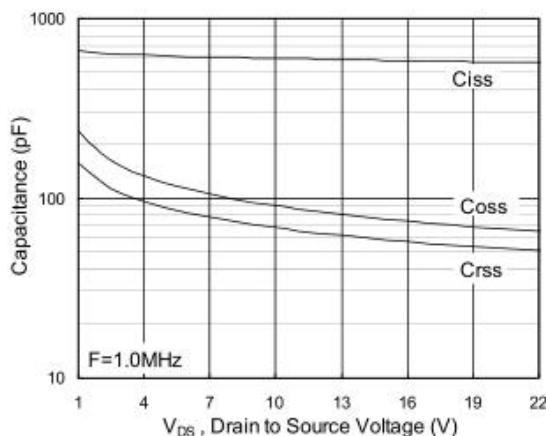


Fig.7 Capacitance

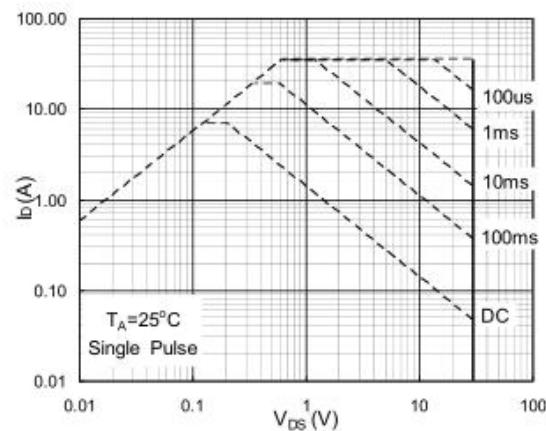


Fig.8 Safe Operating Area

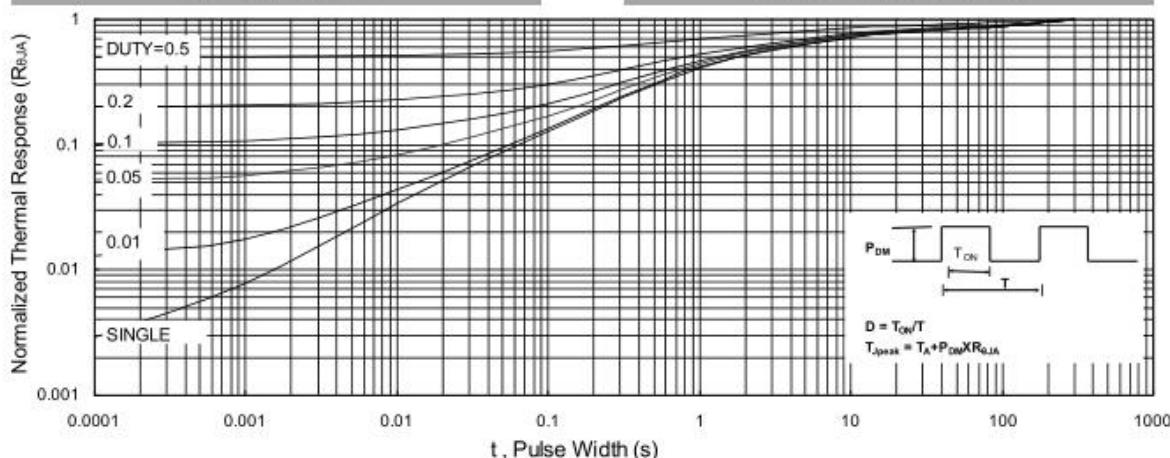


Fig.9 Normalized Maximum Transient Thermal Impedance

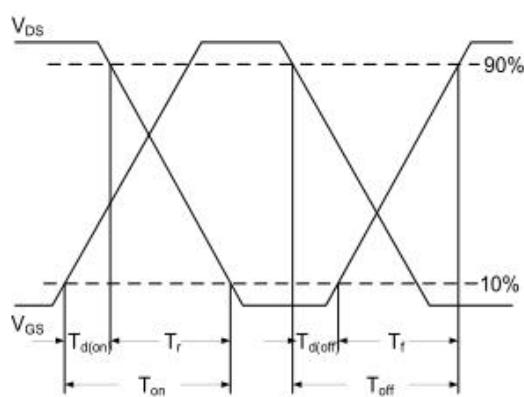


Fig.10 Switching Time Waveform

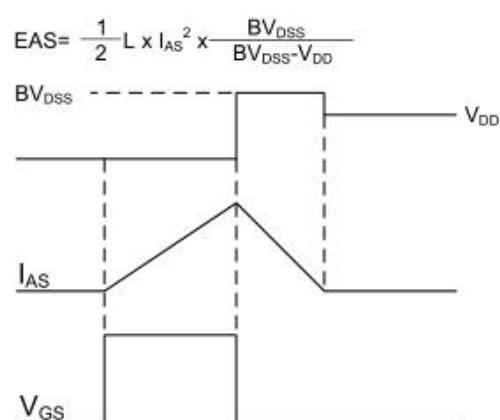


Fig.11 Unclamped Inductive Switching Waveform

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